



**High-Speed CMOS  
4Kx4 SRAM  
with Separate I/O**

**QS8761  
QS8762  
ADVANCE  
INFORMATION**

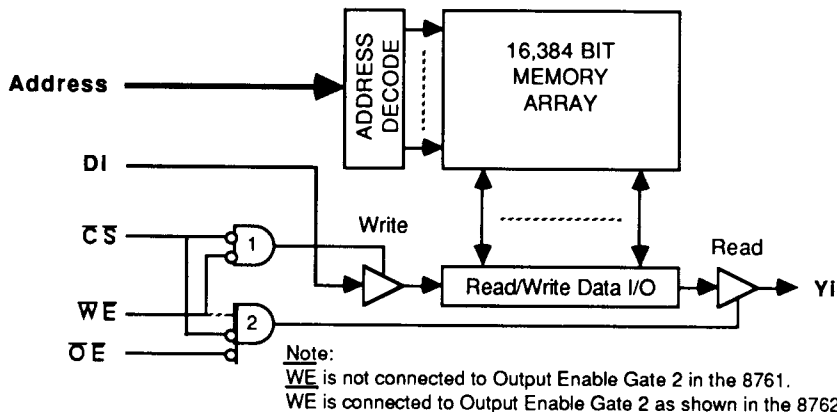
**FEATURES/BENEFITS**

- High Speed Access and Cycle times
- 10ns/12ns/15ns/20ns/25ns Commercial
- 15ns/20ns/25ns/35ns Military
- TTL compatible I/O
- Low power, high-speed QCMOS™ technology
- Military product compliant to MIL-STD-883, Class B
- 6-Transistor cell for high reliability
- Ideal for reliable, dense memory systems
- Available in 24-pin DIP, 24-pin ZIP, 24-pin 300 mil SOJ & SOIC, 28-pin LCC
- Low Standby current
- JEDEC standard pinout

**DESCRIPTION**

The QS8761 and QS8762 are high-speed 16K SRAMs organized as 16Kx4 with separate read and write data buses. In the 8761, the read data outputs follow the inputs during a write; in the 8762, the outputs are disabled during a write. The 8761 and 8762 are manufactured in a high-performance CMOS process, and they are based on a 6-transistor cell design for high reliability of data retention. Their high-speed access times make them useful in cache data RAM, cache tag RAMs, high-speed scratchpad memories, look-up tables, pipelined DSP and bit-slice systems. Low operating power and excellent latch-up and ESD protection are provided.

**FUNCTIONAL BLOCK DIAGRAM**

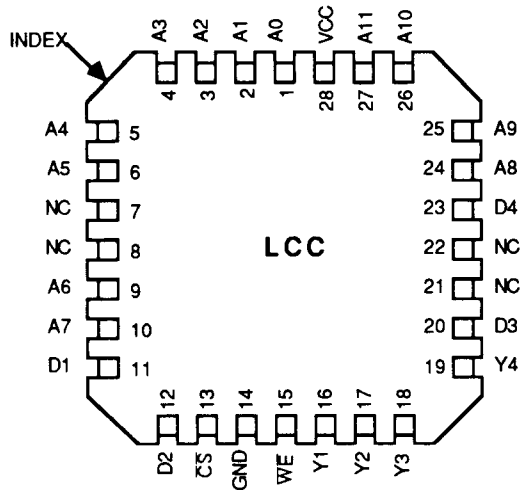
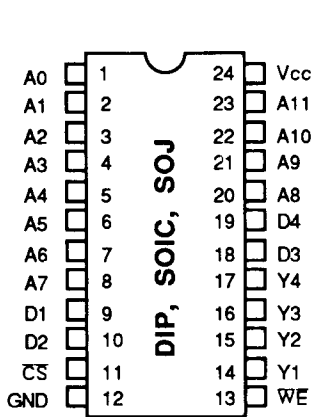


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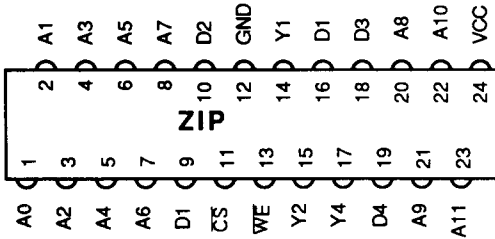
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**PIN CONFIGURATIONS**



**ALL PINS TOP VIEW**



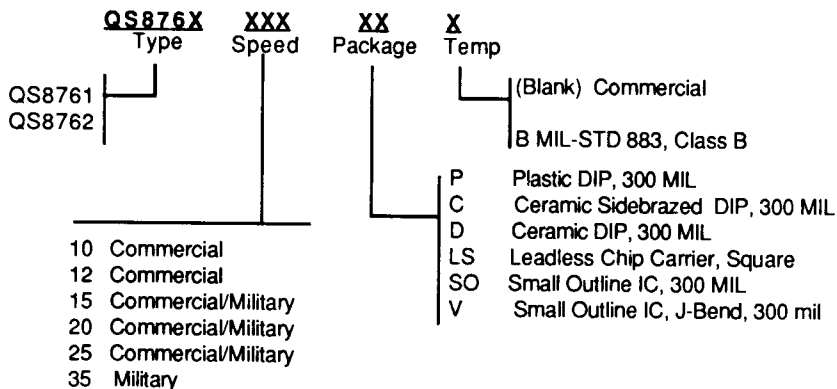
**PIN DESCRIPTION**

Name	I/O	Function
A	I	Address
D	I	Write Data In
Y	O	Read Data Out
CS	I	Chip Select
WE	I	Write Enable
OE	I	Output Enable

**FUNCTION TABLE**

CS	WE	Y Outputs		Power	Function
		8761	8762		
H	X	High Z	High Z	Standby	Deselect
L	H	Data Out	Data Out	Active	Read
L	L	Data In	High Z	Active	Write

## ORDERING INFORMATION



## ABSOLUTE MAXIMUM RATINGS

Supply Voltage to Ground.....	-0.5V to +7.0V.
DC Output Voltage $V_O$ .....	-0.5V to $V_{CC} + 0.5V$ .
DC Input Voltage $V_I$ .....	-0.5V to $V_{CC} + 0.5V$ .
AC Input Voltage (for a pulse width $\leq 20$ ns).....	-3.0 V.
DC Output Current Max. sink current/pin.....	50 mA.
DC Output Current Max. source current/pin.....	30 mA.
TBIAS Temperature Under Bias, COM.....	-65° to +125°C.
TSTG Storage Temperature, COM.....	-65° to +125°C.
TBIAS Temperature Under Bias, MIL.....	-65° to +135°C.
TSTG Storage Temperature, MIL.....	-65° to +155°C.

Note: Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to the maximum ratings for extended periods may affect reliability.

## CAPACITANCE

$T_a = +25^\circ\text{C}$ ,  $f = 1$  MHz

Name	Description	Conditions	Typ	Max	Unit
Cin	Input Capacitance	$V_{in} = 0$ V	6		pF
Cout	Output Capacitance	$V_{out} = 0$ V	7		pF

Note: Capacitance is measured at characterization but not tested at final production.

# QUALITY SEMICONDUCTOR INC.

## DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Commercial TA = 0° C to 70° C, Vcc = 5.0V±10%      Military TA = -55° C to 125° C, Vcc = 5.0V±10%

Symbol	Parameter	Test Conditions	Commercial		Military		Unit
			Min	Max	Min	Max	
Vih	Input HIGH Voltage	Logic High for All Inputs	2.2	6.0	2.2	6.0	Volts
Vil	Input LOW Voltage (1)	Logic Low for All Inputs		0.8		0.8	
Voh	Output HIGH Voltage	Ioh = -4 mA, Vcc = MIN	2.4		2.4		
Vol	Output LOW Voltage	Iol = 8 mA, Vcc = MIN		0.4		0.4	
Ii	Input Leakage	Vcc = MAX, Vin = GND to Vcc		5		10	µA
Io	Output Leakage	Vcc = MAX, Vout = GND to Vcc		5		10	

**Notes:** 1. Transient inputs with Vil not more negative than -3.0 volts are permitted for pulse widths < 20 ns.

## POWER SUPPLY CHARACTERISTICS

Commercial TA = 0° C to 70° C, Vcc = 5.0V±10%      Military TA = -55° C to 125° C, Vcc = 5.0V±10%  
 Vlc = 0.2 V, Vhc = Vcc - 0.2V      At f = 0, no input lines switch; At f = f MAX, RAM is cycling at 1 / t RC

Symbol	Parameter	-10		-12		15		-20		-25/-35		Unit
		C	M	C	M	C	M	C	M	C	M	
Icc1	Static Operating Current, Vcc = MAX Outputs open CS ≤ Vil, f = 0	100	120	100	120	100	120	100	120	100	120	mA
Icc2	Dynamic Operating Current, Vcc = MAX Outputs open CS ≤ Vil, f = f MAX	145	165	135	155	125	145	120	140	110	130	
I <sub>sb</sub>	TTL Standby Current, Vcc = MAX Outputs open CS ≥ Vil, f = f MAX	60	70	60	70	60	70	60	70	60	70	
I <sub>sb1</sub>	Full Standby Current, Vcc = MAX Outputs open CS ≥ Vhc, f = 0 Vin ≤ Vlc or Vin ≥ Vhc	15	20	15	20	15	20	15	20	15	20	

# QUALITY SEMICONDUCTOR INC.

## SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Commercial TA = 0° C to 70°C, Vcc = 5.0V±10%      Military TA = -55°C to 125° C, Vcc = 5.0V±10%  
 See Read Timing Diagrams. All values in nanoseconds unless otherwise noted

Symbol	Parameter (1)	-10 (3)		-12 (3)		-15		-20		-25		-35	
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
<b>READ CYCLE</b>													
t RC	Read Cycle Time	10	-	12	-	15	-	19	-	25	-	35	-
t AA	Address Access Time	-	10	-	12	-	15	-	19	-	25	-	35
t ACS	Chip Select Access Time	-	10	-	12	-	15	-	19	-	25	-	35
t OH	Output Hold from Address Change	2	-	2	-	2	-	3	-	3	-	3	-
t CLZ	Chip Select to Output in Low Z (2)	2	-	2	-	2	-	2	-	2	-	3	-
t CHZ	Chip Select to Output in High Z (2)	-	5	-	5	-	7	-	8	-	10	-	15
t OE	Output Enable to Data Valid (2)	-	5	-	6	-	6	-	8	-	10	-	18
t OLZ	Output Enable to Output in Low Z (2)	2	-	2	-	2	-	2	-	2	-	3	-
t OHZ	Output Enable to Output in High Z (2)	-	4	-	4	-	5	-	7	-	8	-	15
t PU	Chip Select to Power Up Time (2)	0	-	0	-	0	-	0	-	0	-	0	-
t PD	Chip Select to Power Down Time (2)	10	-	12	-	15	-	19	-	25	-	35	-

**Notes:**

- 1) See Test Circuit and Waveforms. Minimums guaranteed but not tested.
- 2) This parameter is guaranteed by design but not tested.
- 3) For Vcc±5% for Commercial Only-Preliminary Data

July1990

QS8761, QS8762

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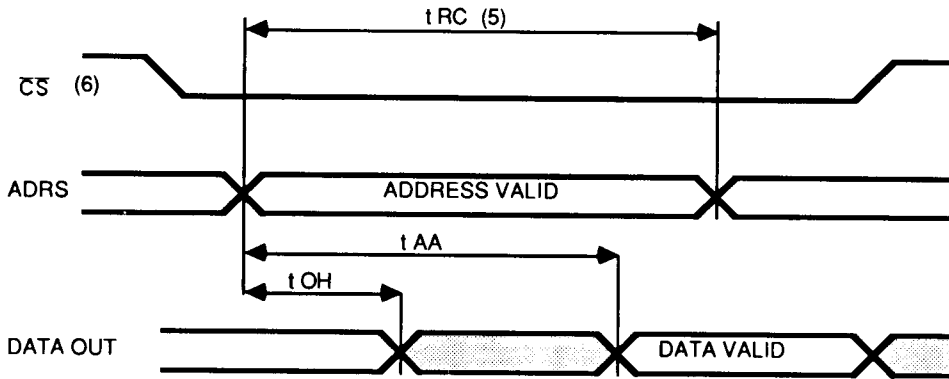
Commercial TA = 0° C to 70° C, Vcc = 5.0V±10%      Military TA = -55° C to 125° C, Vcc = 5.0V±10%  
 See Write Timing Diagrams. All values in nanoseconds unless otherwise noted

Symbol	Parameter (1)	-10 (3)		-12 (3)		-15		-20		-25		-35	
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
<b>WRITE CYCLE</b>													
t <sub>WC</sub>	Write Cycle Time	10	-	12	-	15	-	19	-	25	-	35	-
t <sub>CW</sub>	Chip Select Valid to End of Write	8	-	10	-	13	-	17	-	20	-	30	-
t <sub>AW</sub>	Address Valid to End of Write	8	-	10	-	13	-	17	-	20	-	30	-
t <sub>AS</sub>	Address Setup Time	0	-	0	-	0	-	0	-	0	-	0	-
t <sub>WP</sub>	Write Pulse width	8	-	10	-	12	-	16	-	20	-	30	-
t <sub>WR</sub>	Write Recovery Time	0	-	0	-	0	-	0	-	0	-	0	-
t <sub>DW</sub>	Data Valid to End of Write	5	-	7	-	8	-	10	-	13	-	18	-
t <sub>DH</sub>	Data Hold Time	0	-	0	-	0	-	0	-	0	-	0	-
t <sub>WZ</sub>	Write Enable to Output in Hi Z (2,4)	-	4	-	5	-	6	-	7	-	8	-	12
t <sub>OW</sub>	Output Active from End of Write (4)	2	-	2	-	2	-	2	-	2	-	3	-

**Notes:**

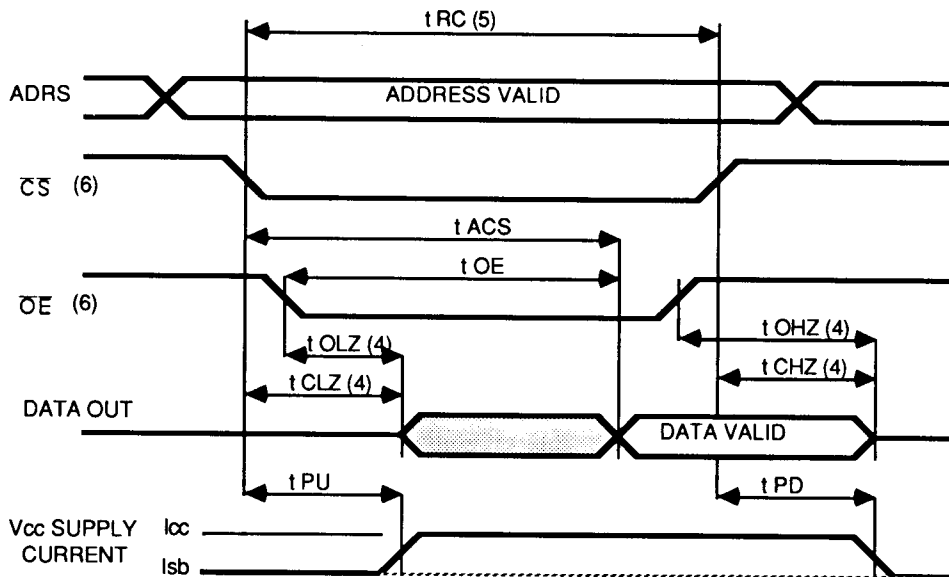
- 1) See Test Circuit and Waveforms. Minimums guaranteed but not tested.
- 2) This parameter is guaranteed by design but not tested.
- 3) For Vcc±5% Commercial Only-Preliminary Data
- 4) 8762 Only. (8761 outputs remain on during write.)

## TIMING WAVEFORMS - READ CYCLE NO. 1 (1,2,3,6)



4

## TIMING WAVEFORMS - READ CYCLE NO. 2 (1,3,6)

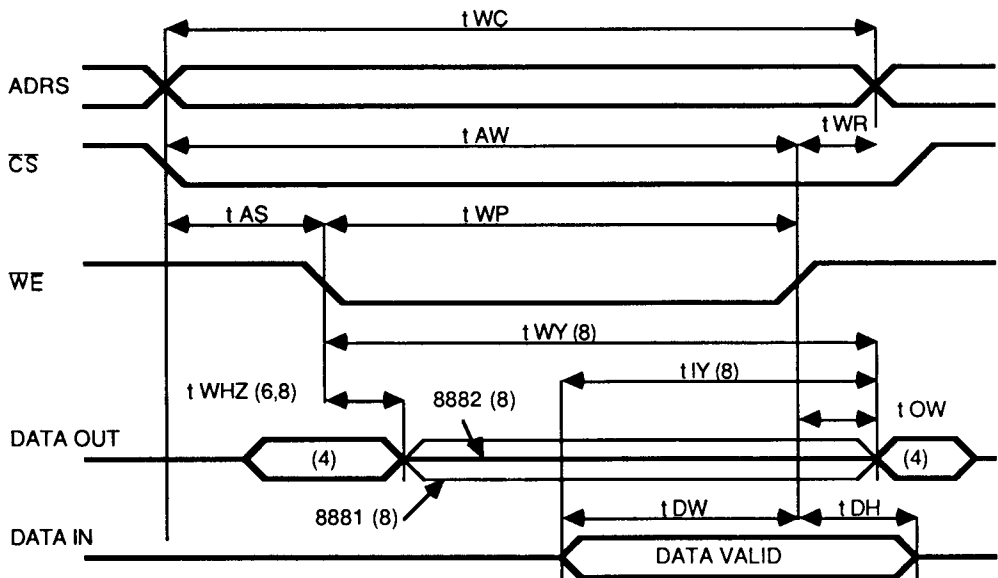


**Notes:**

1. WE is high for Read cycle.
2. CS is low for Read cycle #1.
3. Address is valid to or coincident with CS transition time for Read Cycle #2.
4. Transition to Hi-Z is measured  $\pm 200$  mV change from the prior steady state voltage.
5. All read timings are referenced from the last valid address to the first transitioning address.
6. CS is defined as active during the overlap of CS1 and CS2. Both CS1 and CS2 must be active for read or write.

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## TIMING WAVEFORMS-WRITE CYCLE No. 1 (1,2,3,7 WE controlled timing)

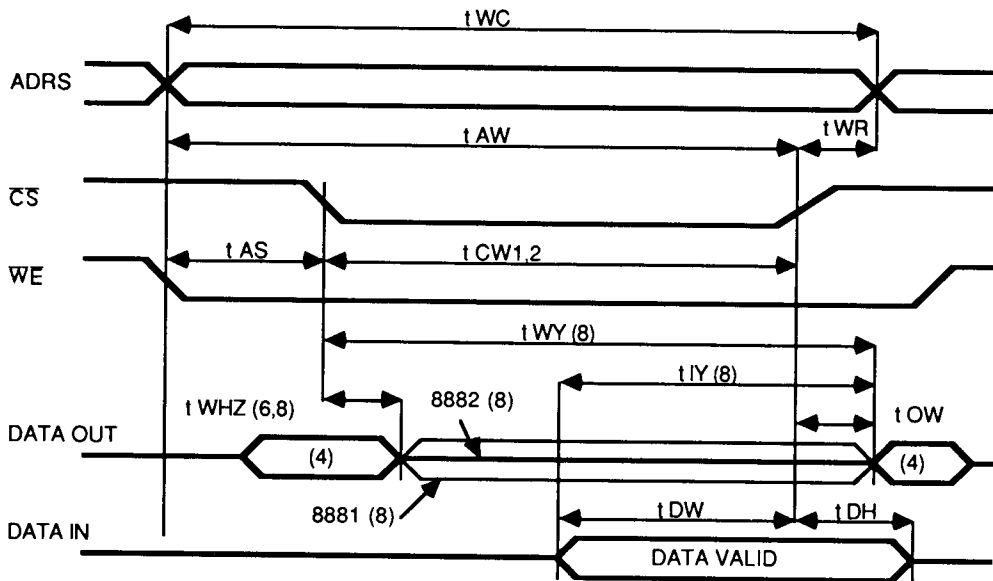


**Notes:**

1. WE or CS must be high during address transitions.
2. A write occurs during the overlap of a low CS and a low WE.
3. tWR is measured from the earlier of CS and WE going high to end of the write cycle.
4. During this period the I/O pins are in the output state and input signals must not be applied.
5. If the CS low transition occurs simultaneously with or after the WE low transition, the output remains in the high impedance state.
6. Transition to Hi-Z is measured  $\pm 200$  mV change from the previous steady state voltage.
7. CS is defined as active during the overlap of CS1 and CS2. Both CS1 and CS2 must be active for read or write.
8. tWY and tIY are data in to data out flow through times during write and are defined for 8761 only.

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## TIMING WAVEFORMS-WRITE CYCLE No. 2 (1,2,3,5,7 $\overline{CS}$ controlled timing)



4

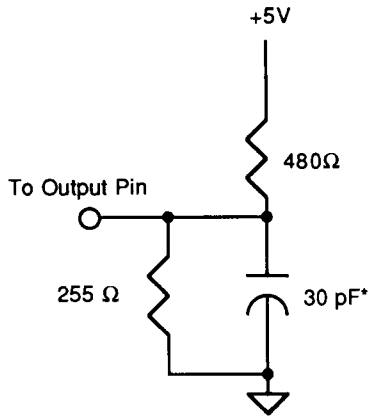
**Notes:**

1. WE or  $\overline{CS}$  must be high during address transitions.
2. A write occurs during the overlap of a low  $\overline{CS}$  and a low WE.
3.  $t_{WR}$  is measured from the earlier of  $\overline{CS}$  and WE going high to end of the write cycle.
4. During this period the I/O pins are in the output state and input signals must not be applied.
5. If the  $\overline{CS}$  low transition occurs simultaneously with or after the WE low transition, the output remains in the high impedance state.
6. Transition to Hi-Z is measured  $\pm 200$  mV change from the previous steady state voltage.
7.  $\overline{CS}$  is defined as active during the overlap of  $\overline{CS1}$  and  $\overline{CS2}$ . Both  $\overline{CS1}$  and  $\overline{CS2}$  must be active for read or write.
8.  $t_{WY}$  and  $t_{IY}$  are data in to data out flow times during write and are defined for 8761 only.

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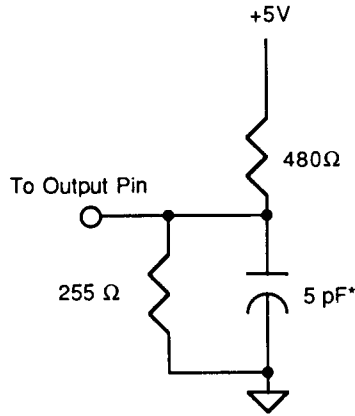
## AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3 ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	See Fig.1&2



\*Includes jig and scope capacitance

Figure 1. Output Load



\*Includes jig and scope capacitance

Figure 2. Output Load

(for tHZ, tLZ, tWZ, tOW)

## FOR MORE INFORMATION CONTACT

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